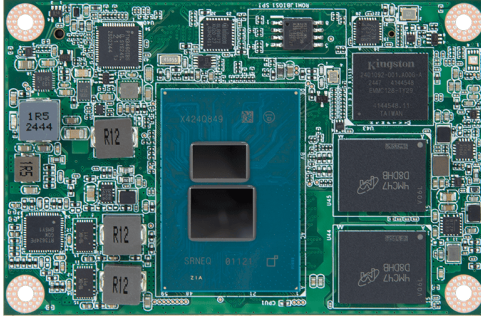


# EmNANO-iX701

Intel® Amston Lake Atom® Mini COM Express® Type 10 CPU Module



## Features

- Soldered onboard Intel Amston lake SoC Processor
- Soldered on board LPDDR5 SDRAM
- Intel® 2.5 Gigabit Ethernet controller
- Single Channel 24-bit LVDS and 1 x DDI port
- Support Intel® Time Coordinated Computing (Intel® TCC) for Intel® Edge Controls for Industrial

## System

CPU	Soldered onboard Intel® Atom® x7211RE 1.3GHz Dual cores TDP 6W Atom® x7433RE 1.5GHz Quad cores TDP 9W
Memory	Soldered onboard LPDDR5 4800MT/s 4GB / 8GB / 16GB SDRAM
BIOS	AMI UEFI BIOS
TPM	TPM2.0

## I/O

USB Port	8 x USB 2.0 ports 2 x USB 3.2 ports
Expansion Bus	4 x PCIe1, LPC, I <sup>2</sup> C, SMBus
Storage	2 x SATA 3.0 ports Soldered onboard eMMC 5.1 (OEM Request)
Ethernet Chipset	1 x Intel® i226 Series 2.5 Gigabit LAN controller
Audio	HD audio link

## Display

Graphic Chipset	Integrated in Intel® Gen12 UHD graphic
Graphic Interface	LCD: Single Channel 24-bit via eDP to LVDS NXP PTN3460 1 x DDI port

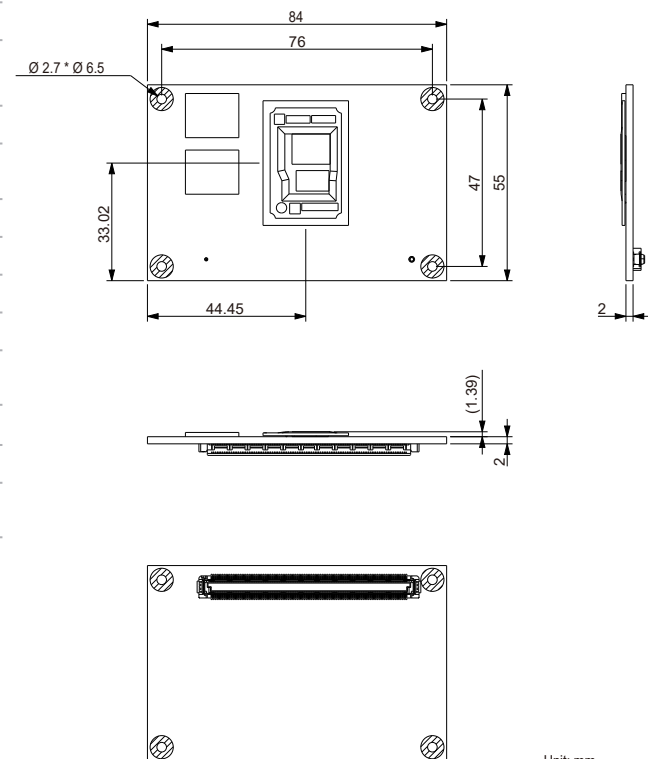
## OS support

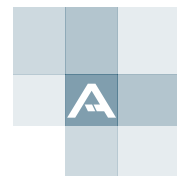
Windows® 10/11 64-bit  
Linux: Ubuntu

## Mechanical & Environmental

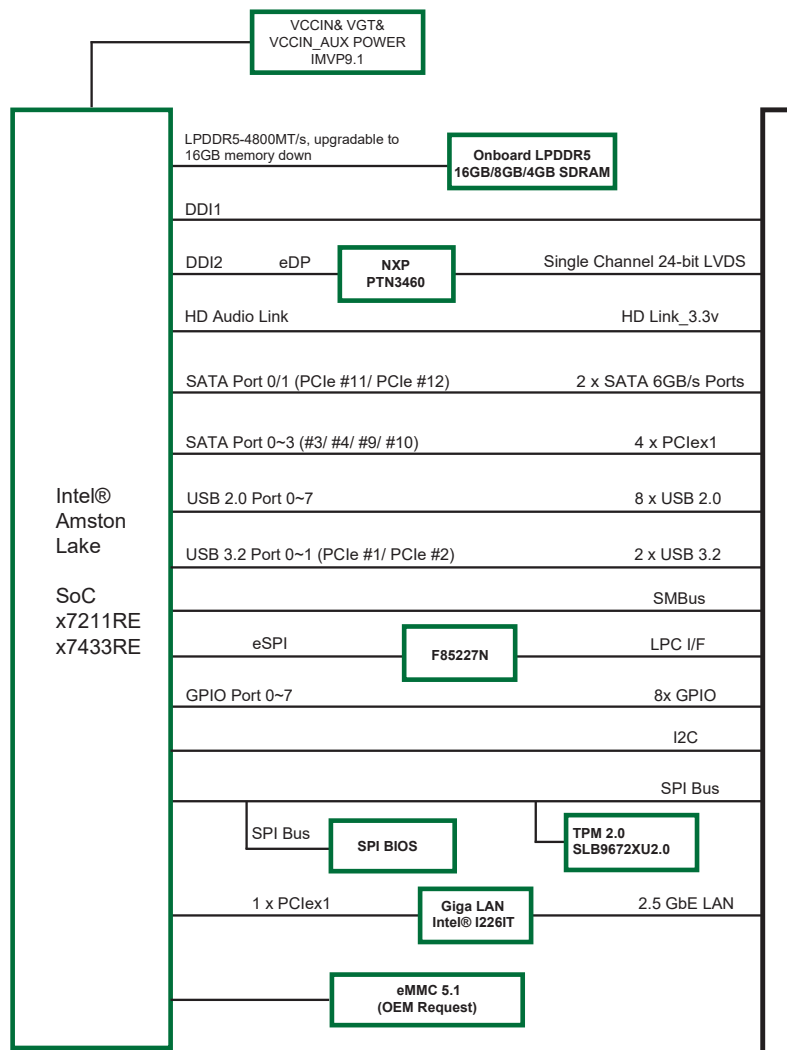
Power Requirement	5V/12V Auto detect
Operating Temp.	-40°C ~ 85°C (-40 ~ 185°F)
Operating Humidity	10 ~ 95% @ 85°C (non-condensing)
Dimensions (L x W)	84 x 55 mm (3.3" x 2.17")

## Dimensions





## Block Diagram



## Ordering Information

EmNANO-iX701-WT-x7211RE-4G	Mini COM Express Type 10 Intel® Amston Lake ATOM x7211RE CPU Module w/4G memory down, -40~85°C
EmNANO-X701-WT-x7433RE-8G	Mini COM Express Type 10 Intel® Amston Lake ATOM x7433RE CPU Module w/8G memory down, -40~85°C
HS-X701-F1	Heat spreader with threaded standoffs
PBN-9007	COM Express Mini evaluation carrier board (EPIC form factor)
CBK-05-9007-00	Cable kit: 1 x USB cable 1 x serial port cable 1 x SATA cable 1 x SATA power cable 1 x PS/2 cable

**\*Note:** An additional wave heat sink was required during the operation process at 85°C.